

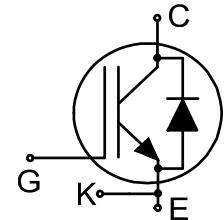
High speed switching series third generation IGBT

Low switching losses IGBT in Highspeed3 technology copacked with soft, fast recovery full current rated anti-parallel Emitter Controlled diode

Features:

High speed H3 technology offers:

- Ultra-low loss switching losses thanks to Kelvin emitter pin package in combination with High speed H3 technology
- High efficiency in hard switching and resonant topologies
- 10µsec short circuit withstand time at $T_{vj}=175^{\circ}\text{C}$
- Easy paralleling capability due to positive temperature coefficient in $V_{CE(sat)}$
- Low EMI
- Low Gate Charge Q_G
- Very soft, fast recovery full current anti-parallel diode
- Maximum junction temperature 175°C
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models:
<http://www.infineon.com/igbt/>



Applications:

- Industrial UPS
- Charger
- Energy Storage
- Three-level Solar String Inverter

Product Validation:

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22



Key Performance and Package Parameters

| Type | V_{CE} | I_C | $V_{CEsat}, T_{vj}=25^{\circ}\text{C}$ | T_{vjmax} | Marking | Package |
|--------------|----------|-------|--|-----------------------|---------|--------------|
| IKY40N120CH3 | 1200V | 40A | 2V | 175°C | K40MCH3 | PG-TO247-4-2 |

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Maximum Ratings

For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

| Parameter | Symbol | Value | Unit |
|---|-------------|----------------------|--------------------|
| Collector-emitter voltage, $T_{vj} \geq 25^{\circ}\text{C}$ | V_{CE} | 1200 | V |
| DC collector current, limited by T_{vjmax} $T_c = 25^{\circ}\text{C}$ value limited by bondwire $T_c = 134^{\circ}\text{C}$ | I_C | 80.0 40.0 | A |
| Pulsed collector current, t_p limited by T_{vjmax} | I_{Cpuls} | 160.0 | A |
| Turn off safe operating area $V_{CE} \leq 1200\text{V}$, $T_{vj} \leq 175^{\circ}\text{C}$, $t_p = 1\mu\text{s}$ | - | 160.0 | A |
| Diode forward current, limited by T_{vjmax} $T_c = 25^{\circ}\text{C}$ value limited by bondwire $T_c = 100^{\circ}\text{C}$ | I_F | 80.0 40.0 | A |
| Diode pulsed current, t_p limited by T_{vjmax} | I_{Fpuls} | 160.0 | A |
| Gate-emitter voltage Transient Gate-emitter voltage ($t_p \leq 10\mu\text{s}$, $D < 0.010$) | V_{GE} | ± 20 ± 30 | V |
| Short circuit withstand time $V_{GE} = 15.0\text{V}$, $V_{CC} \leq 600\text{V}$ Allowed number of short circuits < 1000 Time between short circuits: $\geq 1.0\text{s}$ $T_{vj} = 175^{\circ}\text{C}$ | t_{SC} | 10 | μs |
| Power dissipation $T_c = 25^{\circ}\text{C}$ Power dissipation $T_c = 134^{\circ}\text{C}$ | P_{tot} | 500.0 136.0 | W |
| Operating junction temperature | T_{vj} | -40...+175 | $^{\circ}\text{C}$ |
| Storage temperature | T_{stg} | -55...+150 | $^{\circ}\text{C}$ |
| Soldering temperature, wave soldering 1.6mm (0.063in.) from case for 10s | | 260 | $^{\circ}\text{C}$ |

Thermal Resistance

| Parameter | Symbol | Conditions | Value | | | Unit |
|-----------|--------|------------|-------|------|------|------|
| | | | min. | typ. | max. | |

R_{th} Characteristics

| | | | | | | |
|--|---------------|--|---|---|------|-----|
| IGBT thermal resistance, junction - case | $R_{th(j-c)}$ | | - | - | 0.30 | K/W |
| Diode thermal resistance, junction - case | $R_{th(j-c)}$ | | - | - | 0.50 | K/W |
| Thermal resistance junction - ambient | $R_{th(j-a)}$ | | - | - | 40 | K/W |

High speed switching series third generation IGBT

Electrical Characteristic, at $T_{vj} = 25^{\circ}\text{C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value | | | Unit |
|--------------------------------------|---------------|--|--------|--------------|-----------|---------------|
| | | | min. | typ. | max. | |
| Static Characteristic | | | | | | |
| Collector-emitter breakdown voltage | $V_{(BR)CES}$ | $V_{GE} = 0\text{V}, I_C = 0.50\text{mA}$ | 1200 | - | - | V |
| Collector-emitter saturation voltage | V_{CEsat} | $V_{GE} = 15.0\text{V}, I_C = 40.0\text{A}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | - - | 2.00 2.50 | 2.35 - | V |
| Diode forward voltage | V_F | $V_{GE} = 0\text{V}, I_F = 40.0\text{A}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | - - | 1.90 1.85 | 2.30 - | V |
| Gate-emitter threshold voltage | $V_{GE(th)}$ | $I_C = 1.50\text{mA}, V_{CE} = V_{GE}$ | 5.1 | 5.8 | 6.5 | V |
| Zero gate voltage collector current | I_{CES} | $V_{CE} = 1200\text{V}, V_{GE} = 0\text{V}$ $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | - - | - 3000 | 250 - | μA |
| Gate-emitter leakage current | I_{GES} | $V_{CE} = 0\text{V}, V_{GE} = 20\text{V}$ | - | - | 100 | nA |
| Transconductance | g_{fs} | $V_{CE} = 20\text{V}, I_C = 40.0\text{A}$ | - | 14.0 | - | S |

Electrical Characteristic, at $T_{vj} = 25^{\circ}\text{C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value | | | Unit |
|-------------------------------|-----------|--|-------|-------|------|------|
| | | | min. | typ. | max. | |
| Dynamic Characteristic | | | | | | |
| Input capacitance | C_{ies} | $V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$ | - | 2385 | - | pF |
| Output capacitance | C_{oes} | | - | 235 | - | |
| Reverse transfer capacitance | C_{res} | | - | 132 | - | |
| Gate charge | Q_G | $V_{CC} = 960\text{V}, I_C = 40.0\text{A},$ $V_{GE} = 15\text{V}$ | - | 190.0 | - | nC |

Switching Characteristic, Inductive Load

| Parameter | Symbol | Conditions | Value | | | Unit |
|---|--------------|---|-------|------|------|------|
| | | | min. | typ. | max. | |
| IGBT Characteristic, at $T_{vj} = 25^{\circ}\text{C}$ | | | | | | |
| Turn-on delay time | $t_{d(on)}$ | $T_{vj} = 25^{\circ}\text{C},$ $V_{CC} = 600\text{V}, I_C = 40.0\text{A},$ $V_{GE} = 0.0/15.0\text{V},$ $R_{G(on)} = 12.0\Omega, R_{G(off)} = 12.0\Omega,$ $L\sigma = 70\text{nH}, C\sigma = 67\text{pF}$ $L\sigma, C\sigma$ from Fig. E Energy losses include "tail" and diode reverse recovery. | - | 30 | - | ns |
| Rise time | t_r | | - | 29 | - | ns |
| Turn-off delay time | $t_{d(off)}$ | | - | 280 | - | ns |
| Fall time | t_f | | - | 26 | - | ns |
| Turn-on energy | E_{on} | | - | 2.18 | - | mJ |
| Turn-off energy | E_{off} | | - | 1.30 | - | mJ |
| Total switching energy | E_{ts} | | - | 3.48 | - | mJ |

High speed switching series third generation IGBT

Diode Characteristic, at $T_{vj} = 25^{\circ}\text{C}$

| | | | | | | |
|--|--------------|--|---|------|---|------------------------|
| Diode reverse recovery time | t_{rr} | $T_{vj} = 25^{\circ}\text{C},$ $V_R = 600\text{V},$ $I_F = 40.0\text{A},$ $di_F/dt = 600\text{A}/\mu\text{s}$ | - | 350 | - | ns |
| Diode reverse recovery charge | Q_{rr} | | - | 3.00 | - | μC |
| Diode peak reverse recovery current | I_{rrm} | | - | 22.0 | - | A |
| Diode peak rate of fall of reverse recovery current during t_b | di_{rr}/dt | | - | -188 | - | $\text{A}/\mu\text{s}$ |

Switching Characteristic, Inductive Load

| Parameter | Symbol | Conditions | Value | | | Unit |
|-----------|--------|------------|-------|------|------|------|
| | | | min. | typ. | max. | |

IGBT Characteristic, at $T_{vj} = 175^{\circ}\text{C}$

| | | | | | | |
|------------------------|--------------|--|---|------|---|----|
| Turn-on delay time | $t_{d(on)}$ | $T_{vj} = 175^{\circ}\text{C},$ $V_{CC} = 600\text{V}, I_C = 40.0\text{A},$ $V_{GE} = 0.0/15.0\text{V},$ $R_{G(on)} = 12.0\Omega, R_{G(off)} = 12.0\Omega,$ $L\sigma = 70\text{nH}, C\sigma = 67\text{pF}$ $L\sigma, C\sigma$ from Fig. E Energy losses include "tail" and diode reverse recovery. | - | 29 | - | ns |
| Rise time | t_r | | - | 32 | - | ns |
| Turn-off delay time | $t_{d(off)}$ | | - | 375 | - | ns |
| Fall time | t_f | | - | 64 | - | ns |
| Turn-on energy | E_{on} | | - | 3.10 | - | mJ |
| Turn-off energy | E_{off} | | - | 2.50 | - | mJ |
| Total switching energy | E_{ts} | | - | 5.60 | - | mJ |

Diode Characteristic, at $T_{vj} = 175^{\circ}\text{C}$

| | | | | | | |
|--|--------------|---|---|------|---|------------------------|
| Diode reverse recovery time | t_{rr} | $T_{vj} = 175^{\circ}\text{C},$ $V_R = 600\text{V},$ $I_F = 40.0\text{A},$ $di_F/dt = 600\text{A}/\mu\text{s}$ | - | 550 | - | ns |
| Diode reverse recovery charge | Q_{rr} | | - | 7.50 | - | μC |
| Diode peak reverse recovery current | I_{rrm} | | - | 30.0 | - | A |
| Diode peak rate of fall of reverse recovery current during t_b | di_{rr}/dt | | - | -142 | - | $\text{A}/\mu\text{s}$ |

High speed switching series third generation IGBT

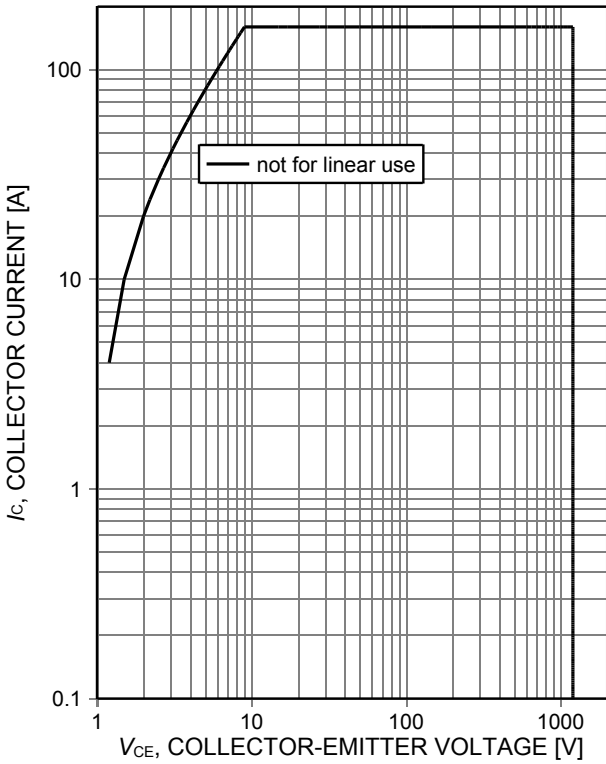


Figure 1. **Forward bias safe operating area**
($D=0$, $T_C=25^\circ\text{C}$, $T_{vj}\leq 175^\circ\text{C}$; $V_{GE}=15\text{V}$)

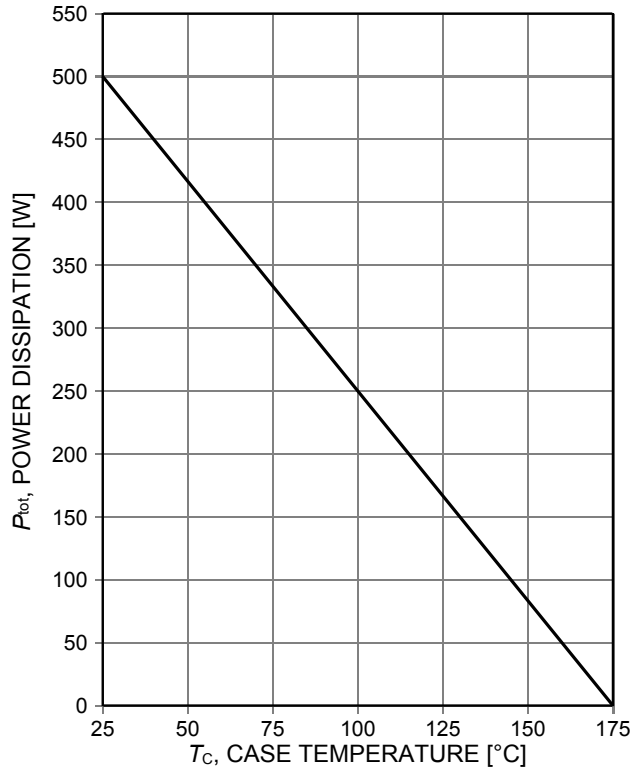


Figure 2. **Power dissipation as a function of case temperature**
($T_{vj}\leq 175^\circ\text{C}$)

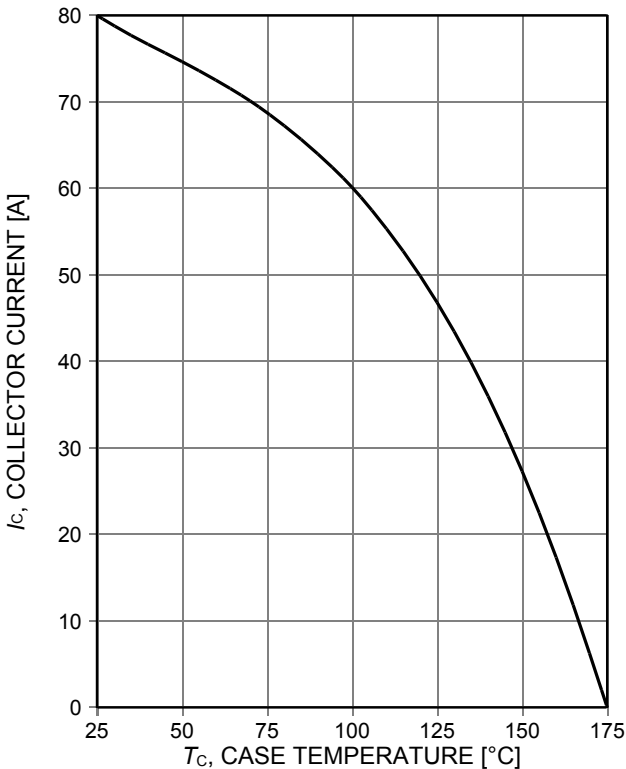


Figure 3. **Collector current as a function of case temperature**
($V_{GE}\geq 15\text{V}$, $T_{vj}\leq 175^\circ\text{C}$)

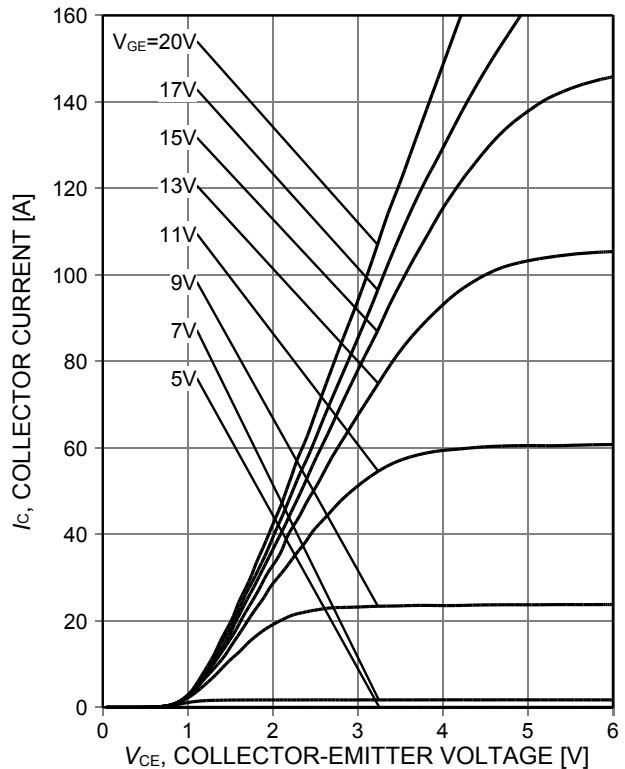


Figure 4. **Typical output characteristic**
($T_{vj}=25^\circ\text{C}$)

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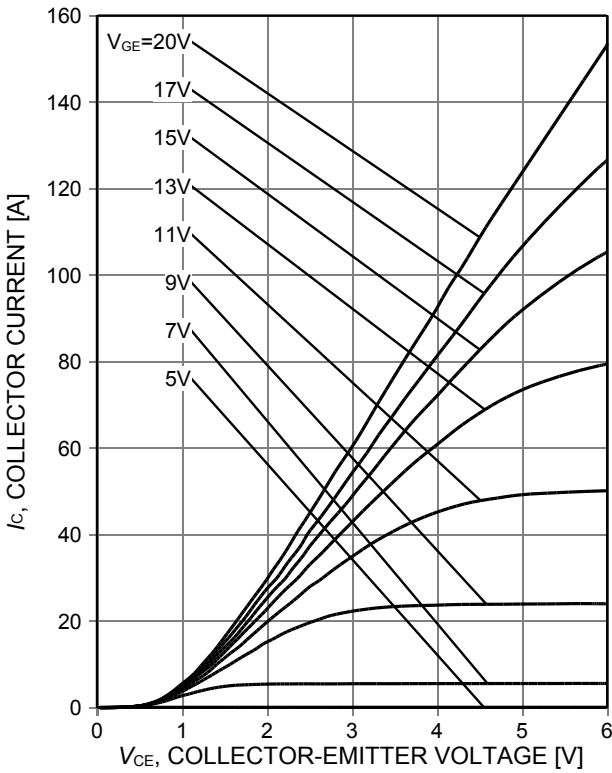


Figure 5. Typical output characteristic ($T_{vj}=175^{\circ}\text{C}$)

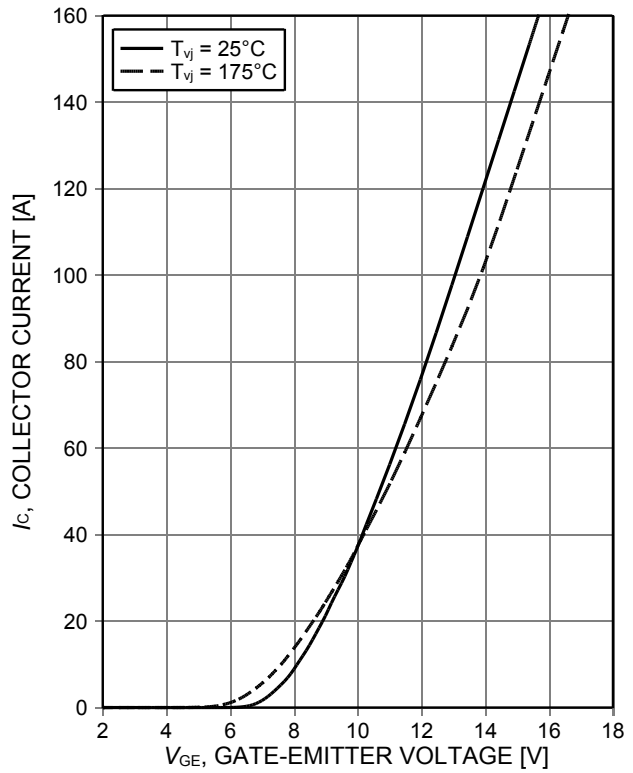


Figure 6. Typical transfer characteristic ($V_{CE}=20\text{V}$)

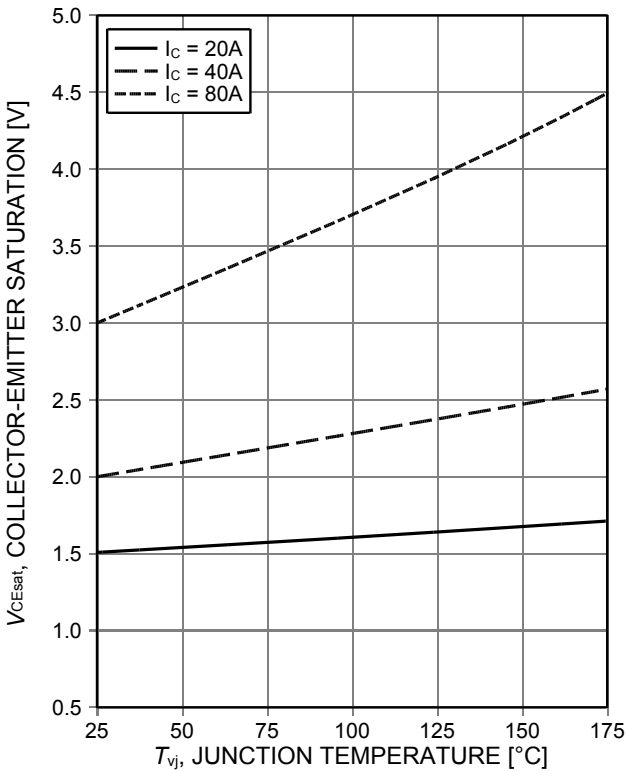


Figure 7. Typical collector-emitter saturation voltage as a function of junction temperature ($V_{GE}=15\text{V}$)

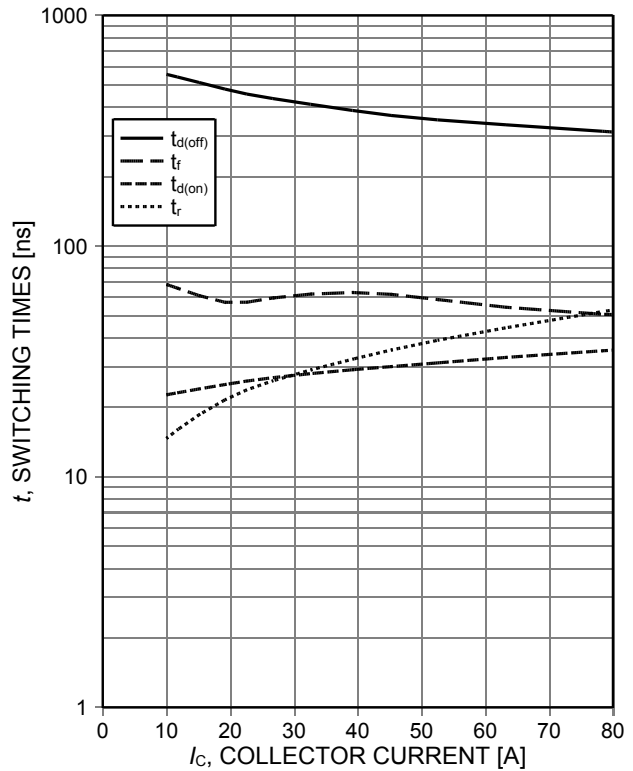


Figure 8. Typical switching times as a function of collector current (inductive load, $T_{vj}=175^{\circ}\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $R_G=12\Omega$, Dynamic test circuit in Figure E)

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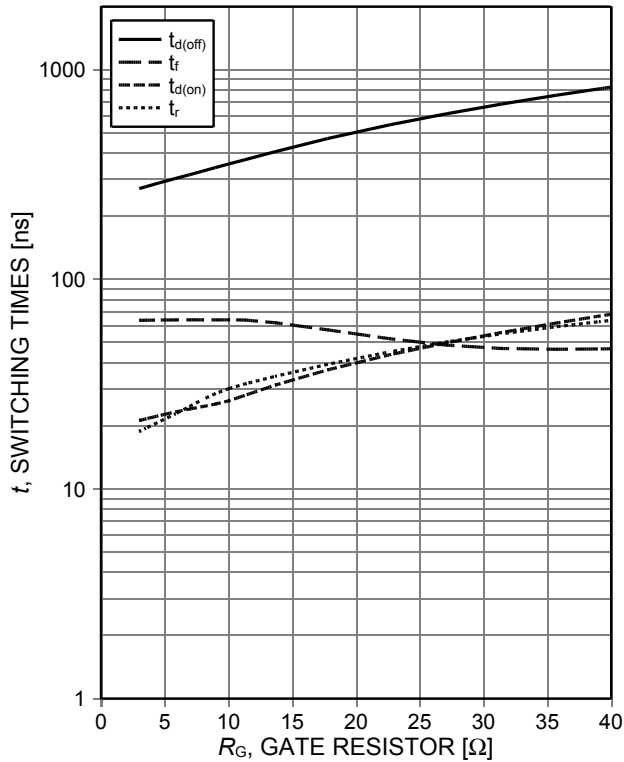


Figure 9. **Typical switching times as a function of gate resistor**
 (inductive load, $T_{vj}=175^{\circ}\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=40\text{A}$, Dynamic test circuit in Figure E)

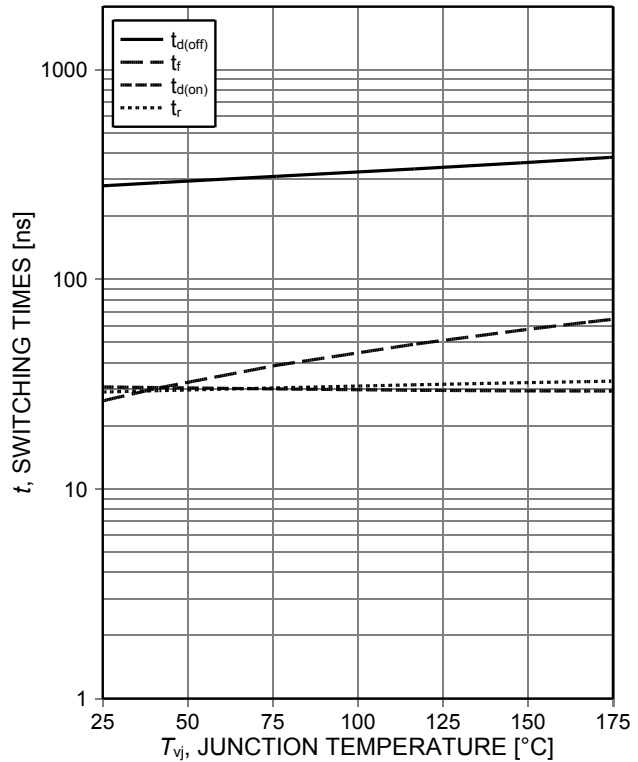


Figure 10. **Typical switching times as a function of junction temperature**
 (inductive load, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=40\text{A}$, $R_G=12\Omega$, Dynamic test circuit in Figure E)

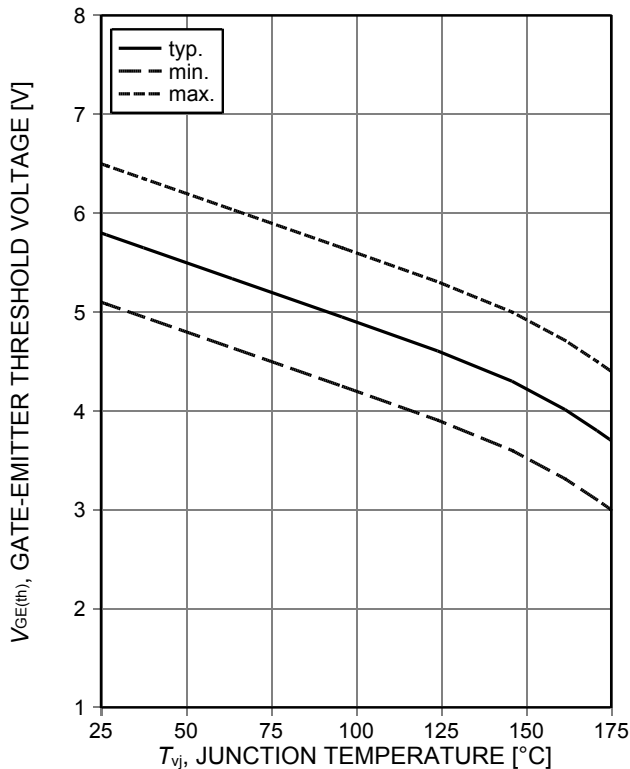


Figure 11. **Gate-emitter threshold voltage as a function of junction temperature**
 ($I_C=1.5\text{mA}$)

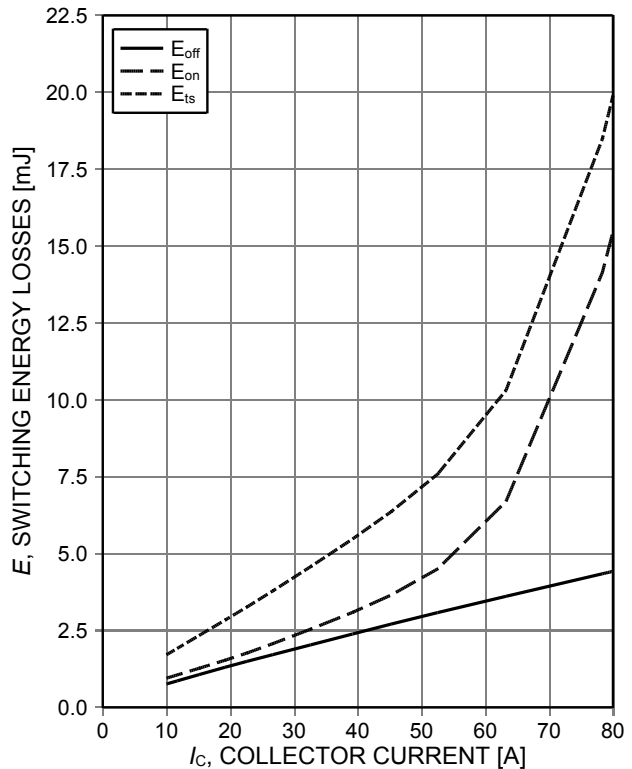


Figure 12. **Typical switching energy losses as a function of collector current**
 (inductive load, $T_{vj}=175^{\circ}\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $R_G=12\Omega$, Dynamic test circuit in Figure E)

High speed switching series third generation IGBT

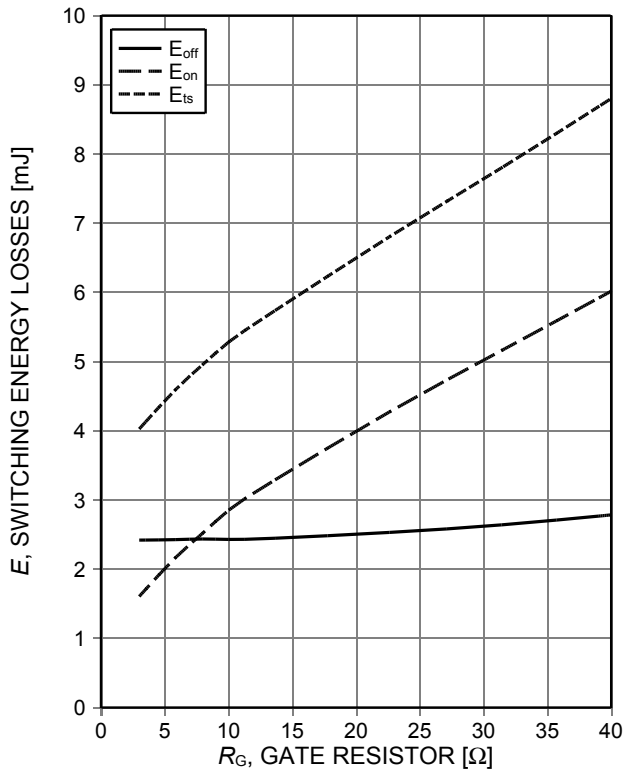


Figure 13. **Typical switching energy losses as a function of gate resistor**
 (inductive load, $T_{vj}=175^{\circ}\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=40\text{A}$, Dynamic test circuit in Figure E)

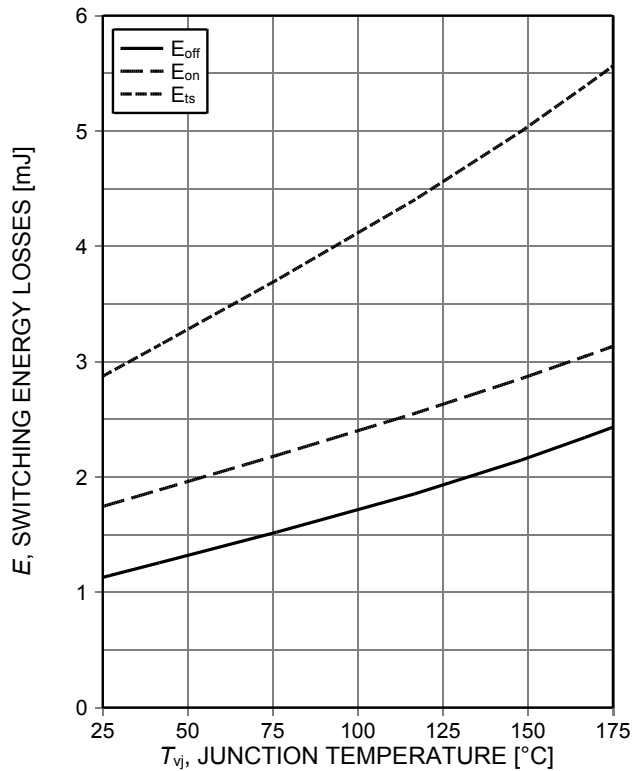


Figure 14. **Typical switching energy losses as a function of junction temperature**
 (inductive load, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=40\text{A}$, $R_G=12\Omega$, Dynamic test circuit in Figure E)

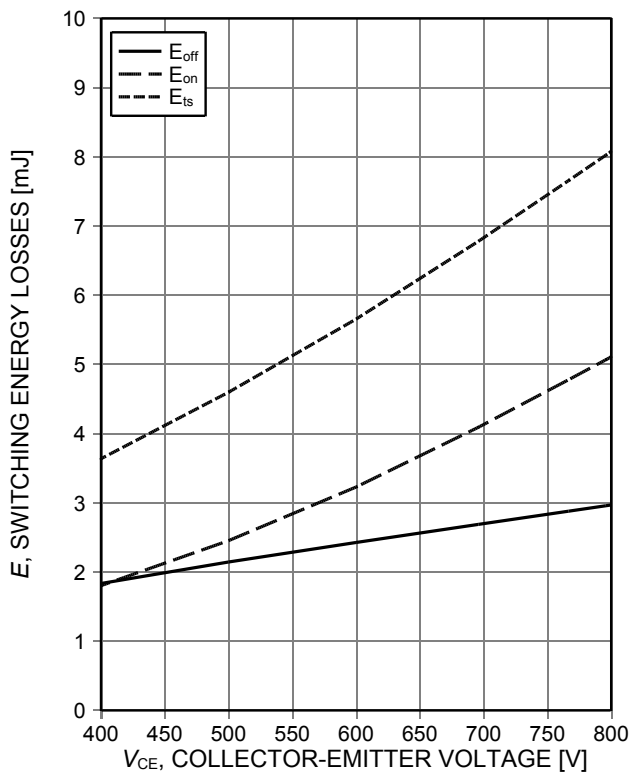


Figure 15. **Typical switching energy losses as a function of collector emitter voltage**
 (inductive load, $T_{vj}=175^{\circ}\text{C}$, $V_{GE}=0/15\text{V}$, $I_C=40\text{A}$, $R_G=12\Omega$, Dynamic test circuit in Figure E)

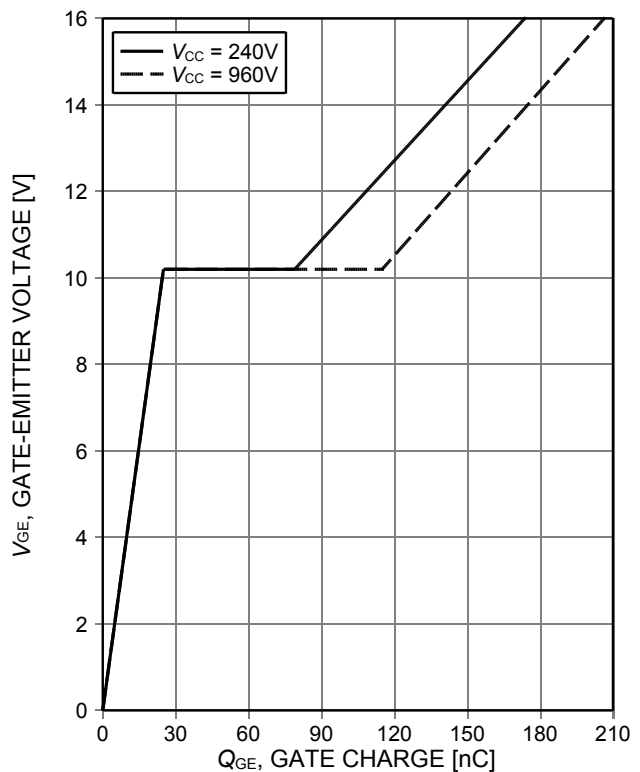


Figure 16. **Typical gate charge**
 ($I_C=40\text{A}$)

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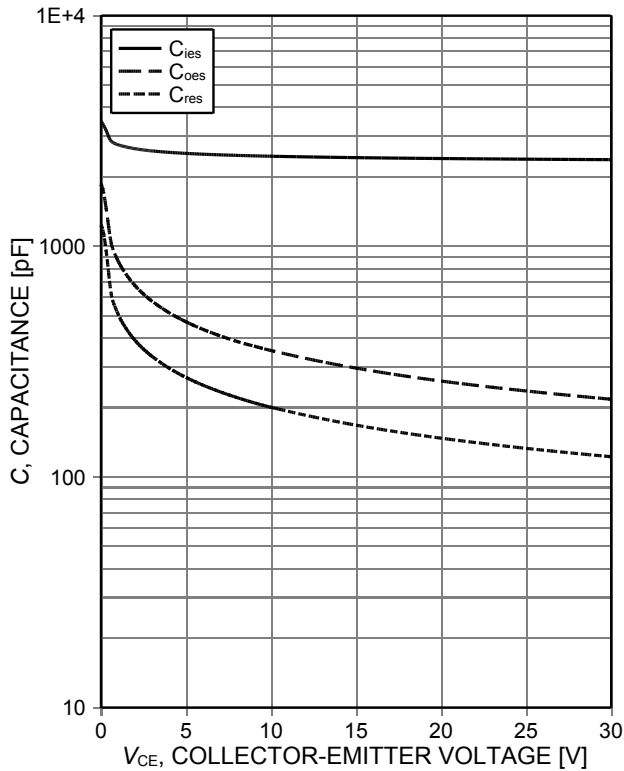


Figure 17. Typical capacitance as a function of collector-emitter voltage ($V_{GE}=0V$, $f=1MHz$)

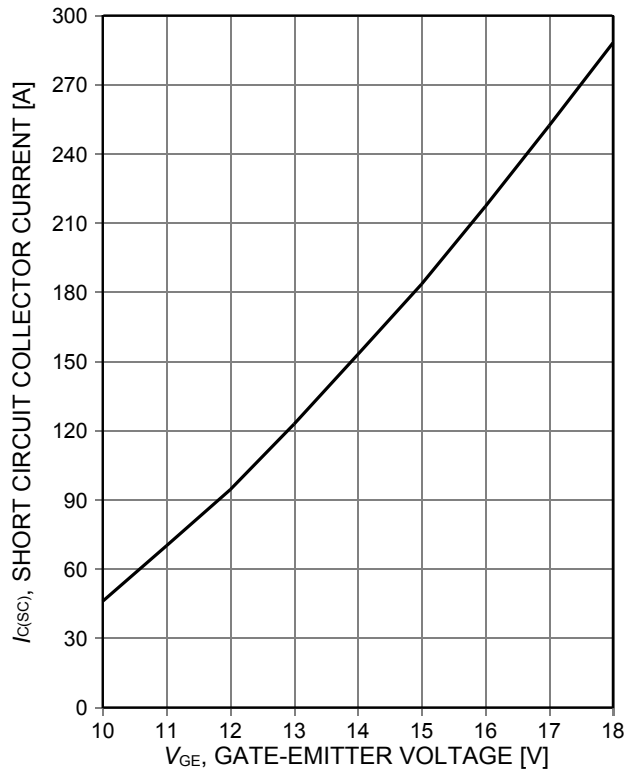


Figure 18. Typical short circuit collector current as a function of gate-emitter voltage ($V_{CE}\leq 600V$, $T_{vj}\leq 175^\circ C$)

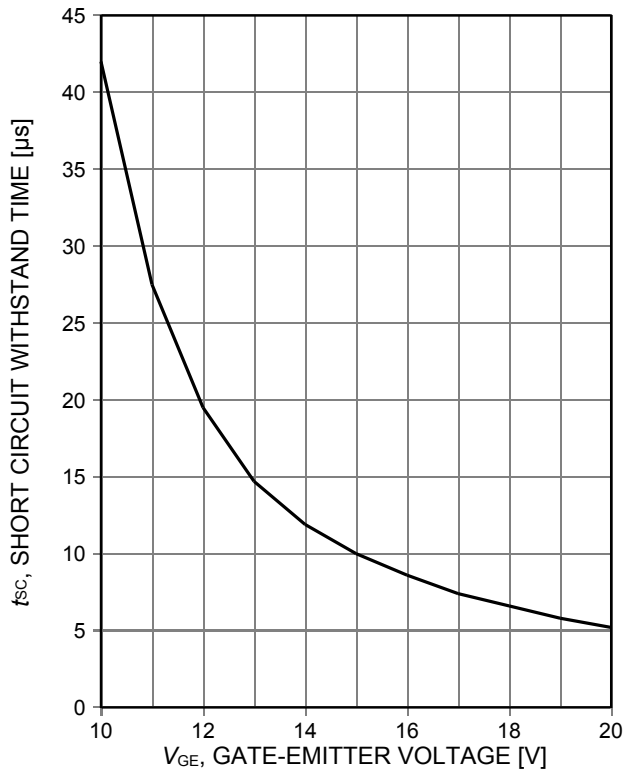


Figure 19. Short circuit withstand time as a function of gate-emitter voltage ($V_{CE}\leq 600V$, start at $T_{vj}\leq 175^\circ C$)

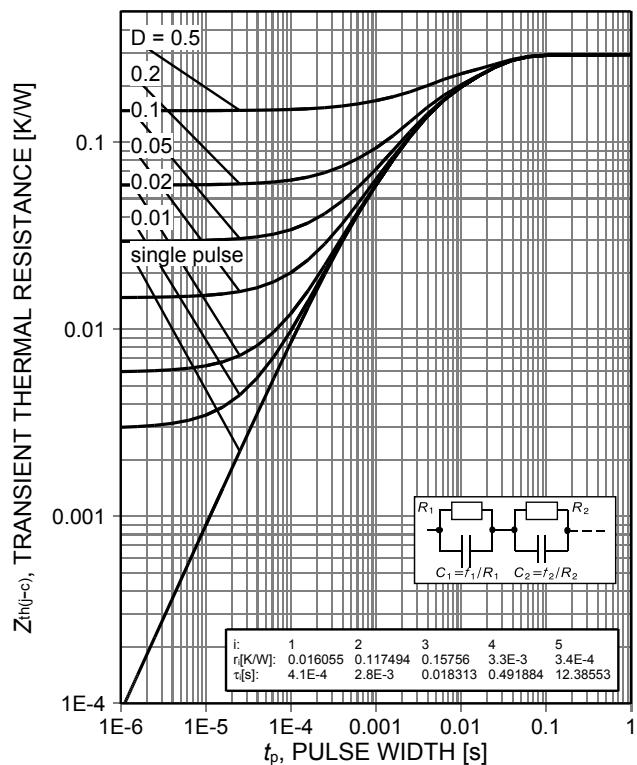


Figure 20. IGBT transient thermal resistance ($D=t_p/T$)

High speed switching series third generation IGBT

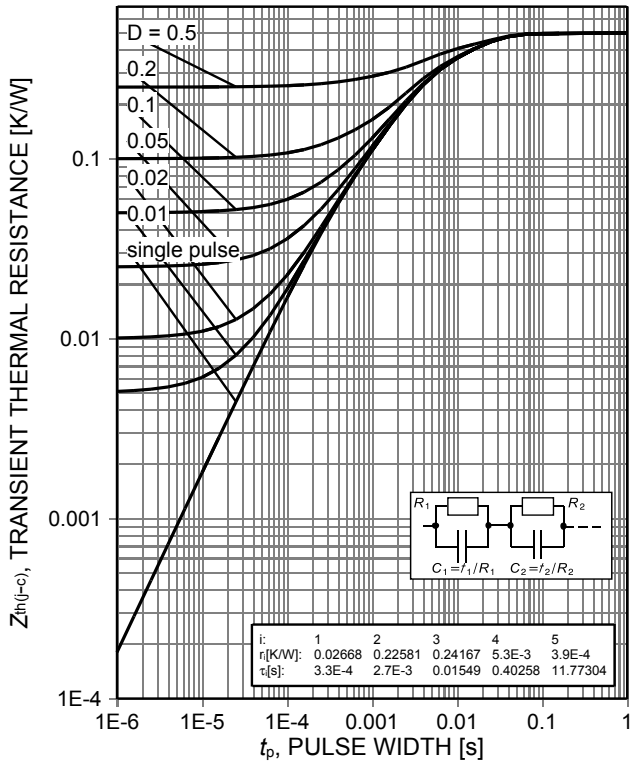


Figure 21. Diode transient thermal impedance as a function of pulse width ($D=t_p/T$)

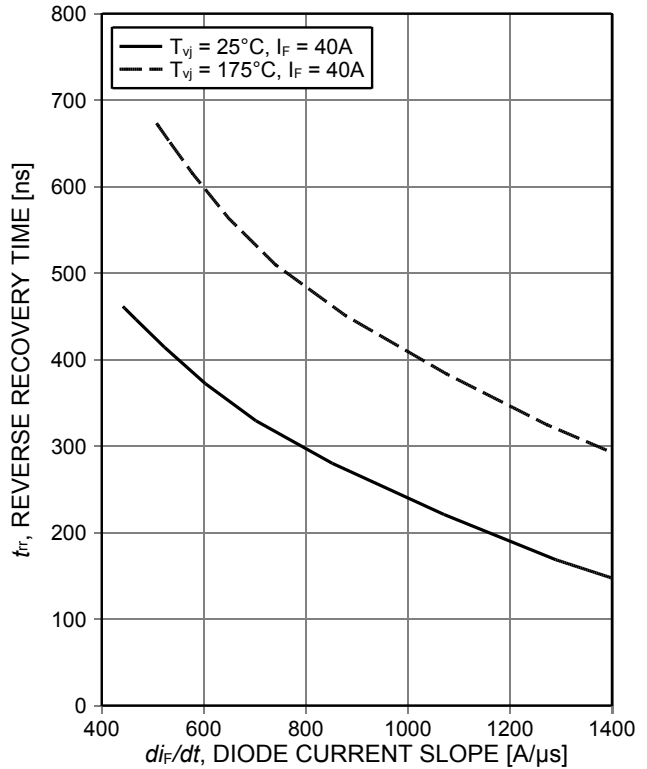


Figure 22. Typical reverse recovery time as a function of diode current slope ($V_R=600V$)

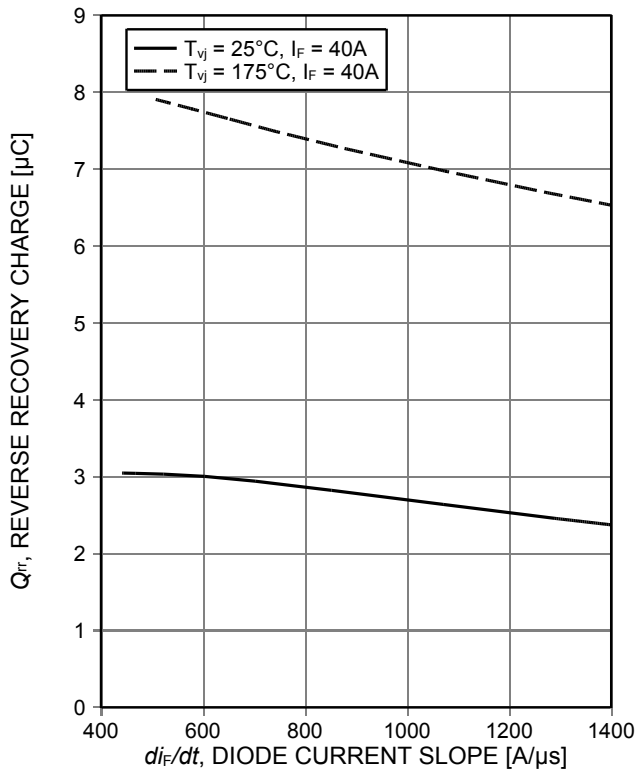


Figure 23. Typical reverse recovery charge as a function of diode current slope ($V_R=600V$)

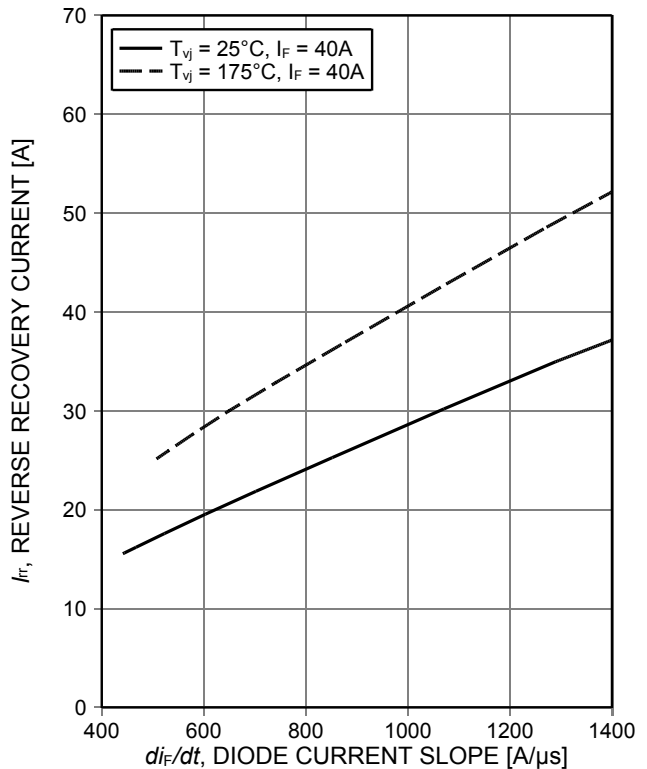


Figure 24. Typical reverse recovery current as a function of diode current slope ($V_R=600V$)

High speed switching series third generation IGBT

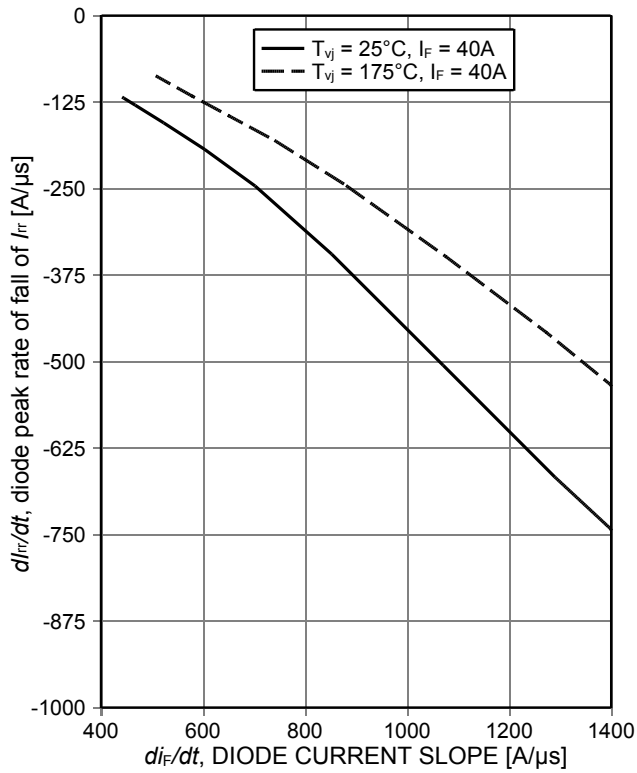


Figure 25. Typical diode peak rate of fall of reverse recovery current as a function of diode current slope (VR=600V)

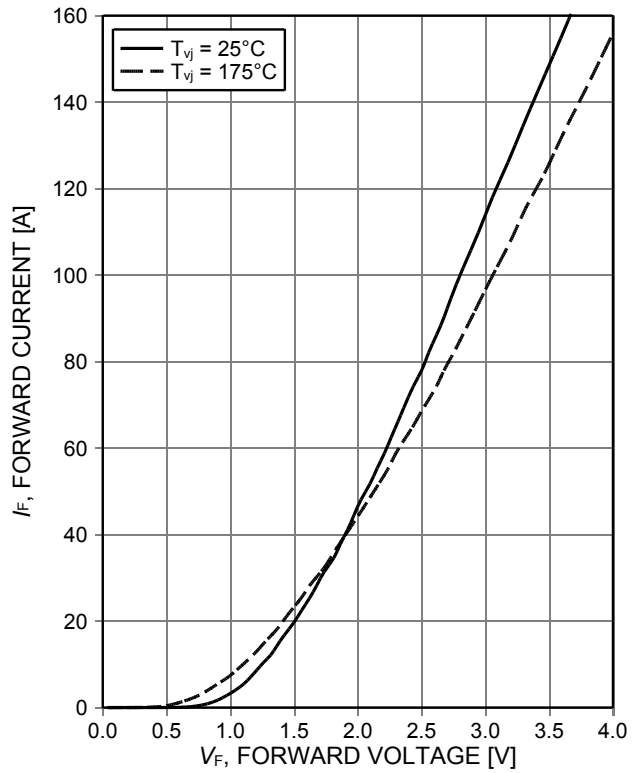


Figure 26. Typical diode forward current as a function of forward voltage

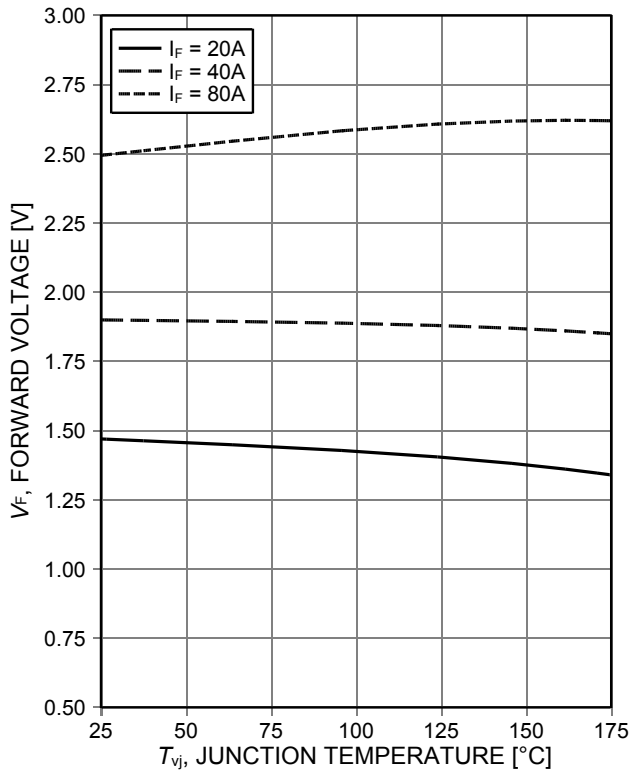
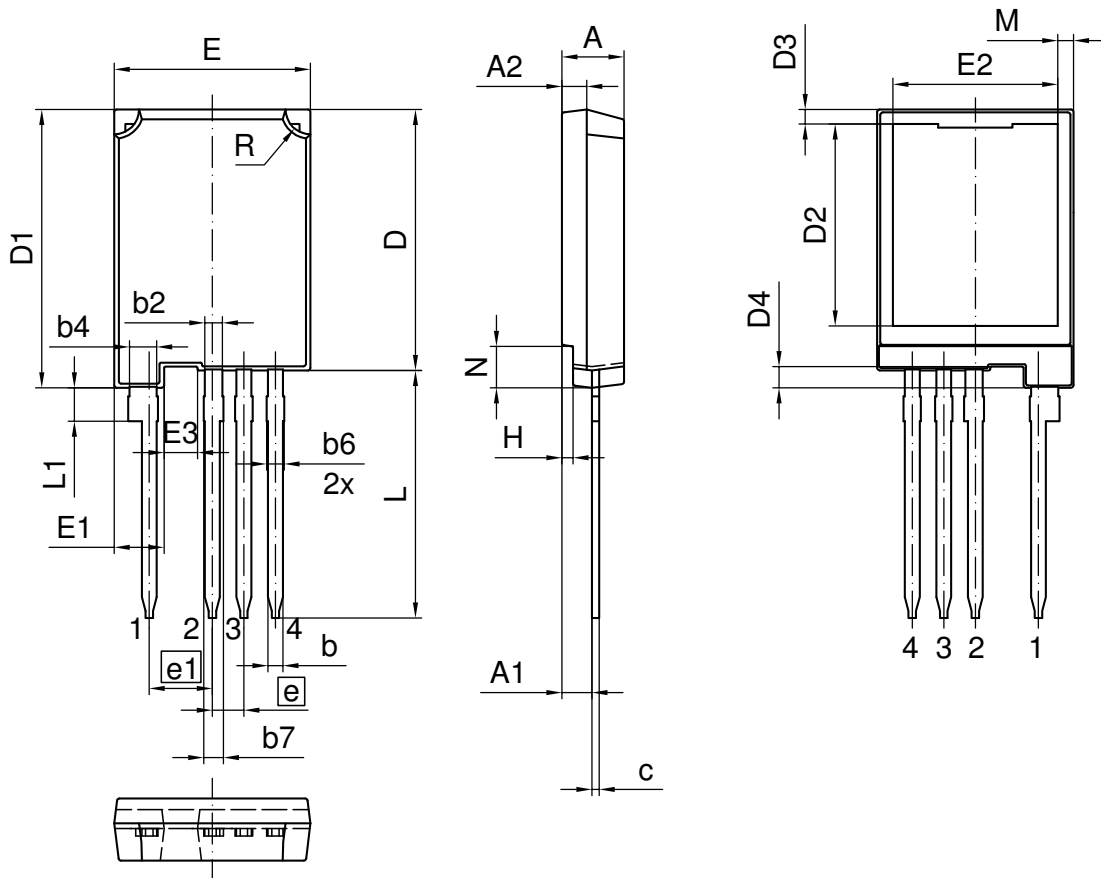


Figure 27. Typical diode forward voltage as a function of junction temperature

PG-TO247-4-2



NOTES:

PACKAGE SURFACE ROUTE BETWEEN PIN 1 & PIN 2 WILL BE 5.1mm MIN.

ALL b... AND c DIMENSIONS INCLUDING PLATING EXCEPT AREA OF CUTTING

| DIMENSION | MILLIMETERS | |
|-----------|-------------|-------|
| | MIN. | MAX. |
| A | 4.9 | 5.1 |
| A1 | 2.31 | 2.51 |
| A2 | 1.9 | 2.1 |
| b | 1.16 | 1.29 |
| b2 | 1.36 | 1.49 |
| b4 | 2.16 | 2.29 |
| b6 | 1.16 | 1.45 |
| b7 | 1.16 | 1.65 |
| c | 0.59 | 0.66 |
| D | 20.9 | 21.1 |
| D1 | 22.3 | 22.5 |
| D2 | 15.95 | 16.55 |
| D3 | 1 | 1.35 |
| D4 | 1.6 | 1.8 |
| E | 15.7 | 15.9 |
| E1 | 3.9 | 4.1 |
| E2 | 13.1 | 13.5 |
| E3 | 2.58 | 2.78 |
| e | 2.54 | |
| e1 | 5.08 | |
| H | 0.8 | 1 |
| L | 19.8 | 20.1 |
| L1 | 2.55 | 2.85 |
| M | 0.97 | 1.57 |
| N | 3.24 | 3.44 |
| R | 1.9 | 2.1 |

| |
|------------------------------------|
| DOCUMENT NO. Z8B00182798 |
| REVISION 01 |
| SCALE 2:1 |
| EUROPEAN PROJECTION |
| ISSUE DATE 23.09.2016 |

High speed switching series third generation IGBT

Testing Conditions

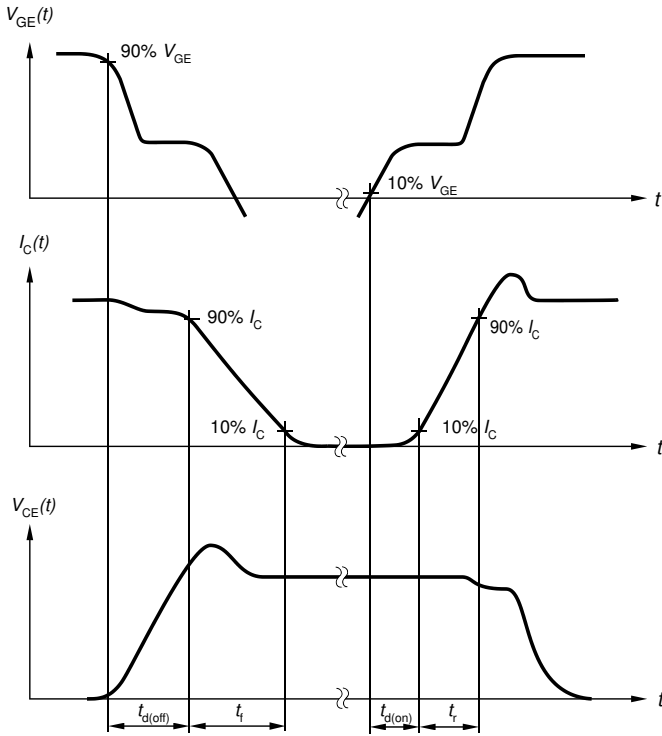


Figure A. Definition of switching times

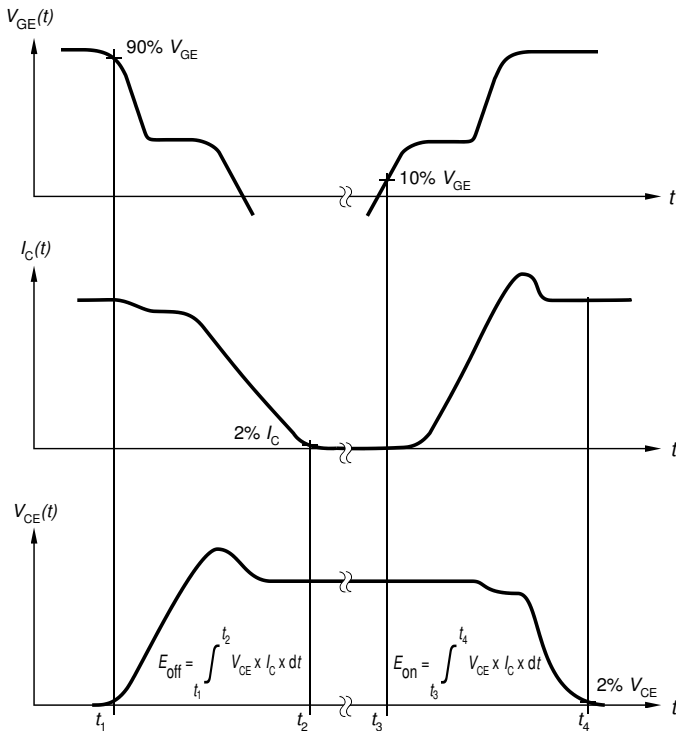


Figure B. Definition of switching losses

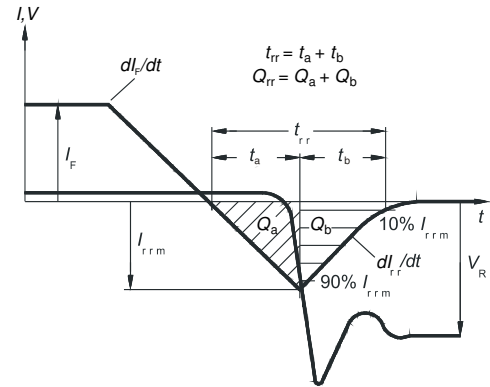


Figure C. Definition of diode switching characteristics

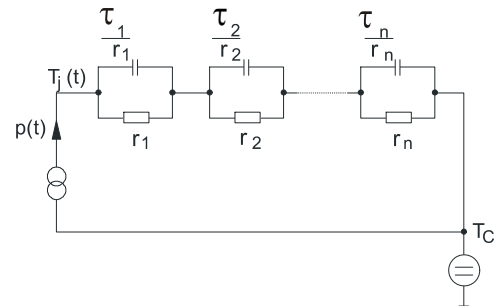


Figure D. Thermal equivalent circuit

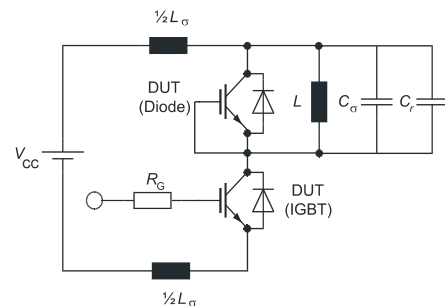


Figure E. Dynamic test circuit
Parasitic inductance L_{σ} ,
parasitic capacitor C_{σ} ,
relief capacitor C_r ,
(only for ZVT switching)

High speed switching series third generation IGBT

Revision History

IKY40N120CH3

Revision: 2019-04-15, Rev. 2.3

Previous Revision

| Revision | Date | Subjects (major changes since last revision) |
|----------|------------|--|
| 2.1 | 2017-04-26 | Final data sheet |
| 2.2 | 2017-06-09 | Update Figure 26 |
| 2.3 | 2019-04-15 | Update condition for V _{geth} page 4 and Fig.11 |

Trademarks

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